



Docket No.: H0498.70155US00  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Hong Yang et al.  
Serial No.: 09/940,072  
Confirmation No.: 3068  
Filed: August 27, 2001  
For: FABRICATION OF CERAMIC MICROSTRUCTURES  
Examiner: C. N. Lopez  
Art Unit: 1731

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Dated: 1/24/07

Signature

**AMENDMENT AFTER ALLOWANCE UNDER 37 C.F.R. 1.312**

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

Applicants respectfully request entry of this amendment under 37 C.F.R. §1.312.

**The Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 11 of this paper.